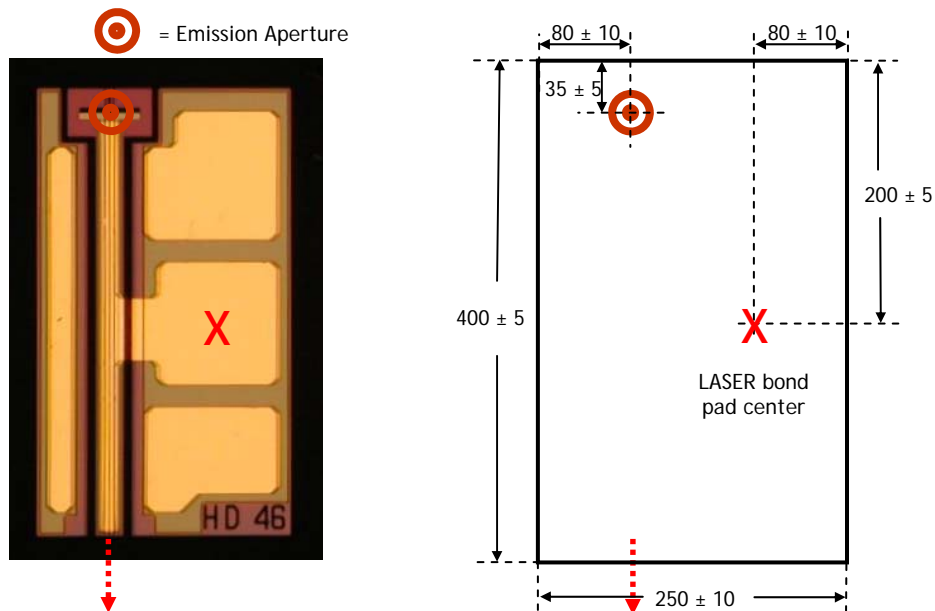




ABSOLUTE MAXIMUM RATINGS						
Parameter	Condition	Symbol	Min.	Typ.	Max.	Unit
Submount Temperature		T	-20	-	95	°C
Storage Temperature		T <sub>St</sub>	-40	-	100	°C
Optical Output Power	CW	P <sub>o</sub>	-	-	15	mW
Laser Reverse Voltage		V <sub>R</sub>	-	-	2	V
Laser Forward Current		I <sub>F</sub>	-	-	150	mA

PHYSICAL CHARACTERISTICS			
Parameter	Symbol	Typical	Unit
Bond Pad	l x w	100 x 100	μm
Chip Dimensions	l x w x h	400 x 250 x 100	μm



ORDERING INFORMATION	
Part Number	Description
131H-02C-LWF11-S01	1310 DFB HCSEL, 2.5G, Commercial Temp (0 to 70°C), Wafer level
131H-02E-LWF11-S01	1310 DFB HCSEL, 2.5G, Extended Temp (-20 to 85°C), Wafer level
131H-02F-LWF11-S01	1310, DFB HCSEL, 2.5G, Extended Industrial Temp (up to 95°C), Wafer level <sup>1</sup>
131H-02C-LCT11-S01	1310 DFB HCSEL, 2.5G, Commercial Temp (0 to 70°C), chip-on-tape
131H-02E-LCT11-S01	1310, DFB HCSEL, 2.5G, Extended Temp (-20 to 85°C), chip-on-tape
131H-02F-LCT11-S01	1310, DFB HCSEL, 2.5G, Extended Industrial Temp (up to 95°C), chip-on-tape <sup>1</sup>
131H-02C-LCG11-S01	1310 DFB HCSEL, 2.5G, Commercial Temp (0 to 70°C), chip on GelPack
131H-02E-LCG11-S01	1310, DFB HCSEL, 2.5G, Extended Temp (-20 to 85°C), chip on GelPack
131H-02F-LCG11-S01	1310 DFB HCSEL, 2.5G, Extended Industrial Temp (up to 95°C), chip on GelPack <sup>1</sup>

1. Lower end of temperature range TBD

